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(54) Title: MANUFACTURING FIRE RETARDANT CIRCUIT BOARDS WITHOUT THE USE OF FIRE RETARDANT RESIN ADDITIVES

(57) Abstract: This invention relates to printed circuit boards having improved fire resistance and improved environmental stability. The invention provides halogen-free fire retardant printed circuit boards incorporating potentially flammable polymers. Flame resistant thermoplastic layers prevent combustion of thermosetting polymers, as well as adding strength to the laminate, resulting in a less brittle thin core than the prior art. The flame resistant circuit board is cost efficient, environmentally safe and has excellent properties, including a decreased probability of shorting, good dielectric breakdown voltage, a smooth surface and good electrical/thermal performance.

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